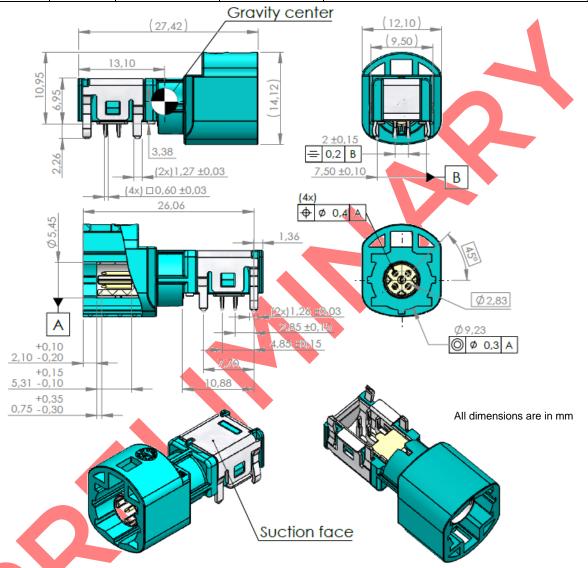
Process: Reflow



R195.160._00

TECHNICAL DATA SHEET

56ate	Product Index	Edited	Approved	Modification
25/06/2019	А	D. GABET	M. DUPONT	Creation



Components	Materials	Plating	
Body	Brass	High temp tin over nickel	
Center contact	Brass	Gold over nickel interface Tin over nickel (Pcb)	
Insulator	LCP	Natural color	
Сар	Brass	High temp tin over nickel	
Housing	Polyamid	UL-94 V0	

Process: Reflow



R195.160._00

TECHNICAL DATA SHEET

<u>Interface</u> Product compatible to AK (German OEM Working Group) interface

Application This terminal has been qualified according to AUDI Specification

Electrical characteristics

Impedance 100Ω Frequency 0-2 GHz

VSWR 17 dB up to 1 Ghz Maxi

Voltage rating100 Veff MaxiDielectric withstanding Voltage250 Veff maxiInsulation resistance5000 MΩRF leakage≥ 75 dBTest voltage250 V rms

Skew Not relevant because of the short electrical length of the receptacle compared

to the length of the cable assembly

Nearend crosstalk < 30 dB Fearend crosstalk < 35 dB

Signal contact resistance 10 m Ω (but not relevant because the contact is not elastic) Outer contact resistance 25 m Ω (but not relevant because the contact is not elastic)

Power current 1.5 A DC

RoHs compliant

EMC screening must be assured by chassis compartment Control box manufacturer is responsible for EMC screening

Mechanical characteristics

Center contact retention, axial force, mating end

Center contact retention, axial force, opposite end

Housing retention

Mating cycles

10 N mini
200 N

≥ 25

Environmental

Operating temperature -40 / +105°C

Hermetic seal Panel leakage

Component weight 4.32 g

Process: Reflow

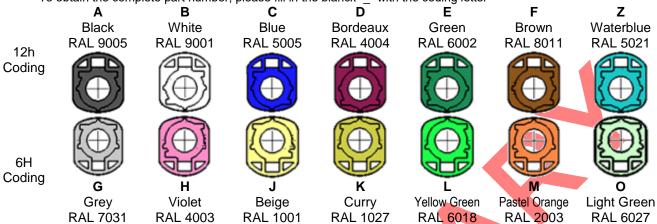


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TECHNICAL DATA SHEET

Codings

To obtain the complete part number, please fill in the blanck "_" with the coding letter ${f A}$ ${f B}$ ${f C}$ ${f D}$ ${f E}$

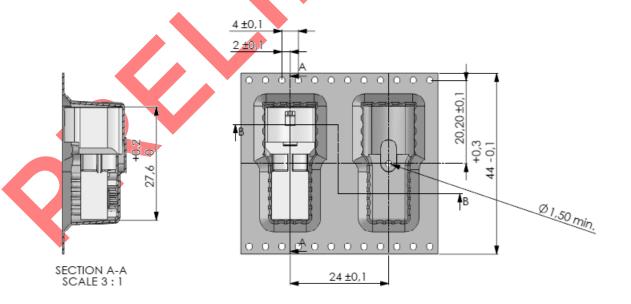


Packaging coding 12H

4 plastic reels inside 1 cardboard box

Primary packaging: plastic reel

- Dimensions: Ø 380 x 44.4mm
- Number of connectors per reel: 250
- Carrier tape description:
 - 44mm width, 24mm pitch.
 - Material: thermoplastic static dissipative. Cover tape material: Thermoplastic antistatic



Process: Reflow



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TECHNICAL DATA SHEET

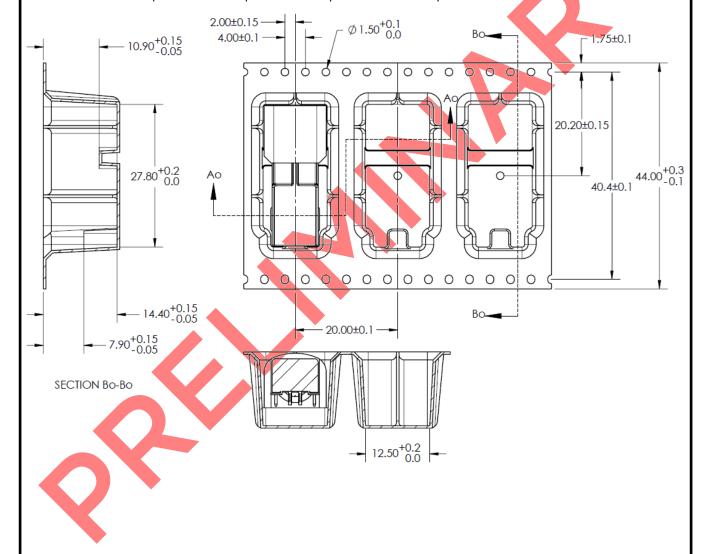
Packaging coding 6h

4 plastic reels inside 1 cardboard box

Primary packaging: plastic reel

- Dimensions: Ø 380 x 44.4mm
- Number of connectors per reel: 300
- Carrier tape description:
 - o 44mm width, 20mm pitch.

Material: thermoplastic static dissipative. Cover tape material: Thermoplastic antistatic



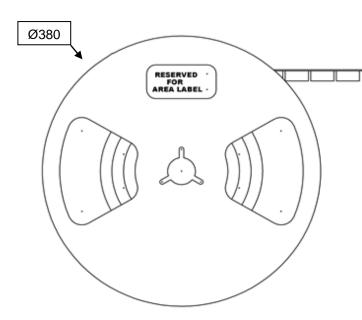
Process: Reflow

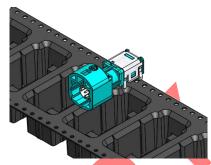


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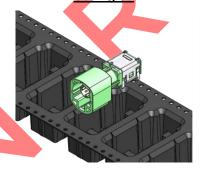
TECHNICAL DATA SHEET

Coding 12H





Coding 6H



Secondary packaging: Cardboard box

- Outside dimensions: 400 x 400 x 260 mm
- Number of reels per cardboard box: 4
- Number of connectors per cardboard box: 1080
- Weight: 8.49 kg



(Picture is not contractual)

Third Packaging: Pallet

- PALLET Europe 1200 x 800mm
- Height: < 1450 mm
- 30 cardbox by pallet
- 32 400 receptacles by complete pallet

Packaging

The product must be used as soon as it is removed from the cells.

Do not leave the product in the open air.

Reels should be stored indoors, in his original unopened packaging, in a controlled climate environment not exceeding -20°C / +40°C and 60% Max. relative humidity.

Reels should be protected from direct sunlight and should be used on a "first-in, first-out" basis.

It is recommended that connector be used within 1 year from the date of manufacture when stored according to the recommended storage condition.

Process: Reflow



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TECHNICAL DATA SHEET

PCB Cut out

- PCB Thickness: 1.6 mm.
- PCB recommended material: FR4 (£r = 4.6).
- 10 metalized holes.
- Solder paste has to be printed onto the land of solder and into holes to permit Pin In Hole Reflow.
- This layout is a recommendation for solderability.
- Design and performances of the PCB will depend on customers choices and RAYDIALL cannot be considered as responsible in case of bad performances.
- A numerical simulation of the PCB is recommended to optimize the RF performance in high frequency.

12H/6H coding layout EDGE OF BOARD 7,5 ±0,05 +0,10 (x4) Ø1 -0,05 [4.8] (x2) R0,4 +0.10 (x4) Ø1,75 - 0,05 10,1 ±0, 0 40,10 6,9 ±0,10 7,7 ±0,05 .85±0.0 85 ±0,05 R1,5 4,8 ±0,10 R0,75 10 ±0,20

Process: Reflow



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TECHNICAL DATA SHEET

Solder procedure

1 - Deposit solder paste "Sn95.5Ag3.8Cu0.7" on mounting zone by screen printing application. We recommend a low Residue Solid Flux.

We advise a thickness of 0.2 millimeters min. (0,008 inch min.).

The holes must be totally filled with cream Verify that the edges of the zone are clean.

2 - Placement of the receptacle on the mounting zone with an automatic machine of "pick and place" type. Video camera is preferred to check the positioning of the component.

Adhesive agents are forbidden on the receptacle.

- 3 Soldering by reflow process. The typical profile to use is given below.
- 4 Clean printed circuit boards.
- 5 Check of solder joints and position of the component by visual inspection

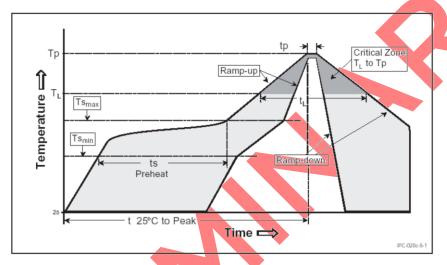


Table 4-2 Pb free process - Package classification reflow temperatures

Table 121 bille process Table go diagonication renew temperatures					
Package	Volume mm ³	Volume mm ³	Volume mm³		
Thickness	<350	350 – 2000	>2000		
< 1,6mm	260 + 0°C*	260 + 0°C*	260 + 0°C*		
>1,6mm / <2,5mm	260 + 0°C*	250 + 0°C*	245 + 0°C*		
>2,5mm	260 + 0°C*	245 + 0°C*	245 + 0°C*		

^{*}Tolerance: The device manufacturer/supplier shall assure process compatibility up to and including the stated classification temperature (this means Peak reflow temperature +0°C. For example 260°C+0°C at the rated MSL level

Profile Feature	Sn-Pb Eutectic assembly	Pb-Free Assembly		
Average Ramp-up Rate (TS _{max} to Tp)	3°C/second max.	3°C/second max.		
Preheat				
 Temperature min (TS_{min}) 	100°C	150°C		
- Temperature max (TS _{max})	150°C	200°C		
- Time (TS _{min} to TS _{max})	60-120 seconds	60-180 seconds		
Time maintained above :				
- Temperature (T _L)	183°C	217°C		
- Time (t∟)	60-150 seconds	60-150 seconds		
Peak/Classification Temperature (T _P)	See Table 4.1	See Table 4.2		
Time within 5°C of actual Peak Temperature (tp)	10-30 seconds	20-40 seconds		
Ramp-down rate	6°C/second max	6°C/second max		
Time 25°C to Peak Temperature	6 minutes max	8 minutes max		

Note: All temperatures refer to topside of the package, measured on the package body surface

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